

# Power Modules: Variants Explanation



FORMS-1014 / Rev. 06

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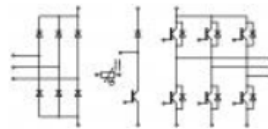
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# Variants Explanation: General Information

## Online Shop Variants:

Customers can choose from a range of product variants regarding:

- Pressure lid type for MiniSKiiP® modules: standard or slim lids
- Thermal Interface Materials (TIM): thermal paste or Phase Change Material (PCM)



**SKiiP 11NAB12T4V1**

MiniSKiiP® 1

V<sub>ces</sub> 1200 V

I<sub>cnom</sub> 8 A

Part Number: 25231580

Net unit weight: 0.03 kg

Tariff Number: 85412900

Country of Origin: Germany

Manufacturer: SEMIKRON

[datasheet](#)

[More about variants](#)

Choose variant

- M20: item+Std. Lid
- M10: item+Slim Lid
- M25: item +Std. Lid+HpTp
- M21: item+Std. Lid+P12
- M15: item +Slim Lid+HpTp
- M11: item+Slim Lid+P12
- M00: module only
- M01: item+P12

Variant Code	Module only	Module + Slim Lid	Module + Standard Lid
No TIM applied	M00	M10	M20
Paste P12	M01	M11	M21
Paste HpTp	M05	M15	M25
PCM HALA P8	M04	-	-

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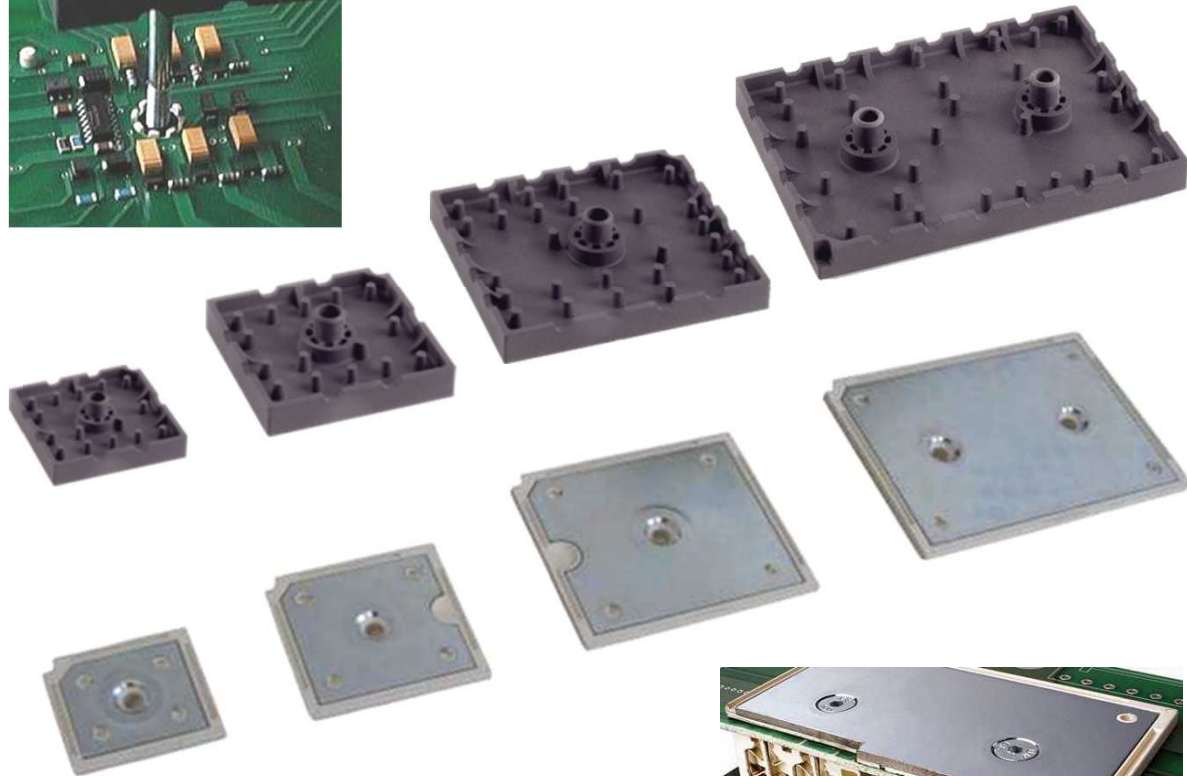
# Variants Explanation: MiniSKiiP® Lid Options

## - Standard Lid:

Lid height of 6.5 mm.  
Ample space for SMD components (max. height 3.5 mm)



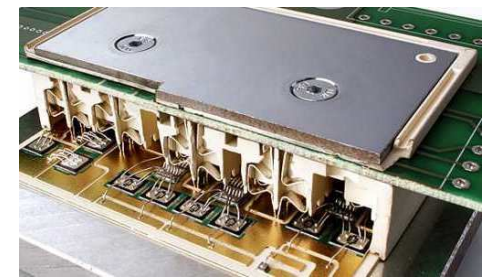
Standard Lid 6.5 mm



## - Slim Lid:

Lid height of 2.8 mm.  
Slim solution for minimum height requirement

Slim Lid 2.8 mm



## Variants Explanation: Thermal Interface Materials

### - With P12:

For a fast and easy assembly of the module on the heat sink with an optimum thickness of thermal paste layer.

### - With HpTp:

Improved thermal paste with a better performance

$$\lambda_{\text{paste}} = 2.5 \text{ W/(mK)}$$

### - With HALA P8:

PCM with excellent conductive property which is solid at room temperature and silicone free.

